AMP | Mark I

TE Internal #: 171457-1

PCB Mount Header, Horizontal, Wire-to-Board, 21 Position, 5 mm [. 197 in] Centerline, Fully Shrouded, Tin (Sn), Through Hole - Screw,

Natural, Mark I

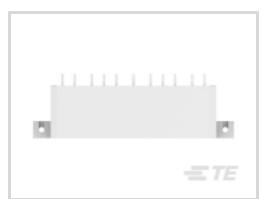
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Connectors > PCB Connectors > PCB Headers & Receptacles











PCB Connector Type: PCB Mount Header

PCB Mount Orientation: Horizontal
Connector System: Wire-to-Board

Number of Positions: 21

Number of Rows: 2

Features

Product Type Features

Mixed & Hybrid Header	No
PCB Connector Type	PCB Mount Header
Connector System	Wire-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Connector Product Type	Connector Assembly
Configuration Features	
PCB Mount Orientation	Horizontal
Number of Positions	21
Number of Rows	2

Natural

Contact Features

Primary Product Color

Body Features



Contact Size	3mm	
Contact Mating Area Plating Material	Tin (Sn)	
Contact Type	Tab	
Termination Features		
Termination Method to PCB	Through Hole - Screw	

Mechanical Attachment

PCB Mount Retention	Without
PCB Mount Alignment	With
Connector Mounting Type	Board Mount
Mating Alignment	With

Housing Features

Centerline (Pitch)	5 mm[.197 in]
Contonino (i itali)	5 11111[.177 111]

Usage Conditions

Operating Temperature Range	-30 - 105 °C[-22 - 221 °F]

Packaging Features

Packaging Method	Trav	
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Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 240°C

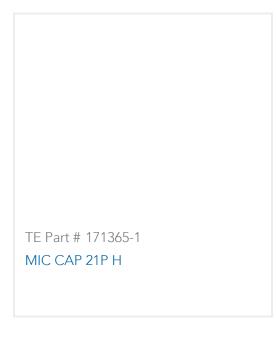
Product Compliance Disclaimer

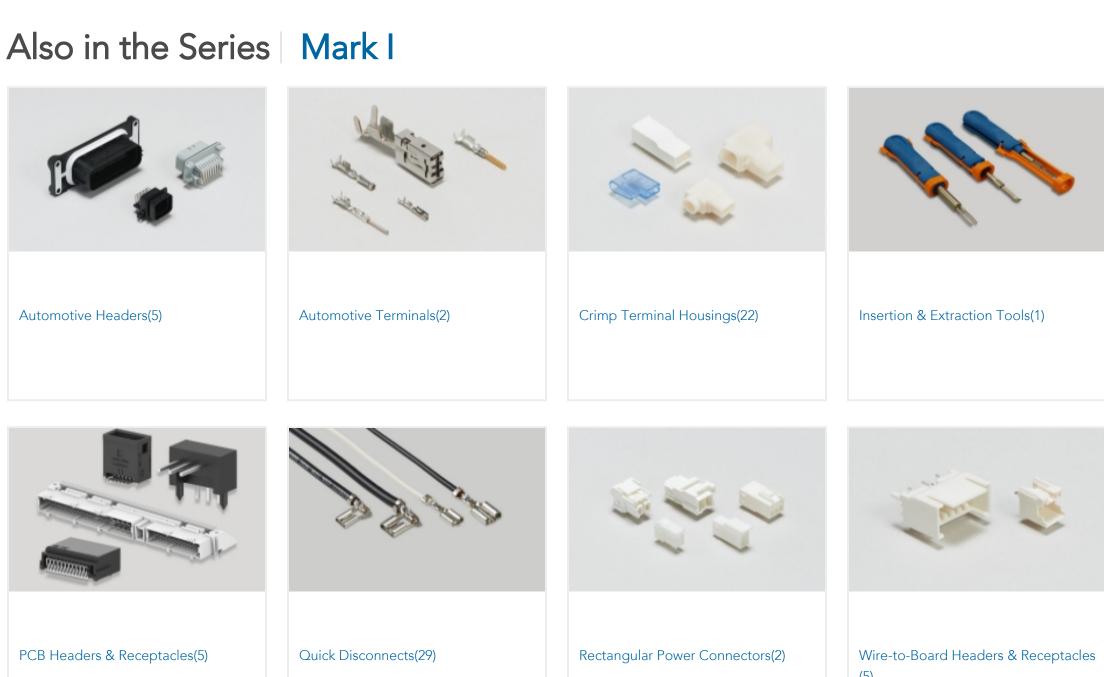
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent



chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Customers Also Bought







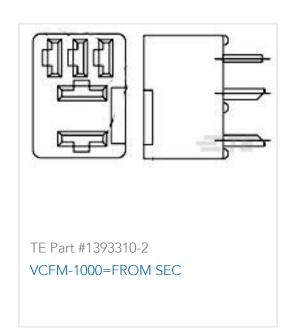
















Documents

CAD Files

3D PDF

English

Customer View Model

ENG_CVM_171457-1_K1.2d_dxf.zip

English

Customer View Model

ENG_CVM_171457-1_K1.3d_igs.zip

English

Customer View Model

ENG_CVM_171457-1_K1.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

Product Specifications

Multi-Interlock Mark II Connector for Printed Circuit Board

Japanese

Product Specification

Japanese

PCB Mount Header, Horizontal, Wire-to-Board, 21 Position, 5 mm [.197 in] Centerline, Fully Shrouded, Tin (Sn), Through Hole - Screw, Natural, Mark I



Multi-Interlock Mark II Connector for Wire to Board Termination

English

Product Specification

English

Agency Approvals

Agency Approval Document

English